

MMBTA63LT1G, MMBTA64LT1G, SMMBTA64LT1G



ON Semiconductor®

<http://onsemi.com>

Darlington Transistors

PNP Silicon

Features

- AEC-Q101 Qualified and PPAP Capable
- S Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements
- These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant*

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Collector - Emitter Voltage	V_{CES}	-30	Vdc
Collector - Base Voltage	V_{CBO}	-30	Vdc
Emitter - Base Voltage	V_{EBO}	-10	Vdc
Collector Current - Continuous	I_C	-500	mAdc

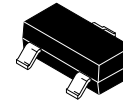
THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Total Device Dissipation FR-5 Board, (Note 1) $T_A = 25^\circ\text{C}$ Derate above 25°C	P_D	225 1.8	mW mW/ $^\circ\text{C}$
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	556	$^\circ\text{C}/\text{W}$
Total Device Dissipation Alumina Substrate, (Note 2) $T_A = 25^\circ\text{C}$ Derate above 25°C	P_D	300 2.4	mW mW/ $^\circ\text{C}$
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	417	$^\circ\text{C}/\text{W}$
Junction and Storage Temperature	T_J, T_{stg}	-55 to +150	$^\circ\text{C}$

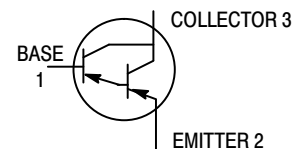
Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

1. FR-5 = 1.0 x 0.75 x 0.062 in.
2. Alumina = 0.4 x 0.3 x 0.024 in. 99.5% alumina.

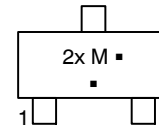
*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.



SOT-23 (TO-236)
CASE 318
STYLE 6



MARKING DIAGRAM



2x = Device Code
 x = U for MMBTA63LT1G
 x = V for MMBTA64LT1G
 SMMBTA64LT1G
 M = Date Code*
 ■ = Pb-Free Package

(Note: Microdot may be in either location)
 *Date Code orientation and/or overbar may vary depending upon manufacturing location.

ORDERING INFORMATION

Device	Package	Shipping†
MMBTA63LT1G	SOT-23 (Pb-Free)	3,000 / Tape & Reel
MMBTA64LT1G	SOT-23 (Pb-Free)	3,000 / Tape & Reel
SMMBTA64LT1G	SOT-23 (Pb-Free)	3,000 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

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ELECTRICAL CHARACTERISTICS ($T_A = 25^\circ\text{C}$ unless otherwise noted)

Characteristic	Symbol	Min	Max	Unit
OFF CHARACTERISTICS				
Collector - Emitter Breakdown Voltage ($I_C = -100 \mu\text{Adc}$)	$V_{(BR)CEO}$	-30	-	Vdc
Collector Cutoff Current ($V_{CB} = -30 \text{Vdc}$)	I_{CBO}	-	-100	nAdc
Emitter Cutoff Current ($V_{EB} = -10 \text{Vdc}$)	I_{EBO}	-	-100	nAdc
ON CHARACTERISTICS				
DC Current Gain (Note 3) ($I_C = -10 \text{mAdc}$, $V_{CE} = -5.0 \text{Vdc}$) MMBTA63 ($I_C = -10 \text{mAdc}$, $V_{CE} = -5.0 \text{Vdc}$) MMBTA64, SMMBTA64 ($I_C = -100 \text{mAdc}$, $V_{CE} = -5.0 \text{Vdc}$) MMBTA63 ($I_C = -100 \text{mAdc}$, $V_{CE} = -5.0 \text{Vdc}$) MMBTA64, SMMBTA64	h_{FE}			-
		5,000	-	
		10,000	-	
		10,000	-	
		20,000	-	
Collector - Emitter Saturation Voltage ($I_C = -100 \text{mAdc}$, $I_B = -0.1 \text{mAdc}$)	$V_{CE(sat)}$	-	-1.5	Vdc
Base - Emitter On Voltage ($I_C = -100 \text{mAdc}$, $V_{CE} = -5.0 \text{Vdc}$)	$V_{BE(on)}$	-	-2.0	Vdc
SMALL-SIGNAL CHARACTERISTICS				
Current - Gain - Bandwidth Product ($I_C = -10 \text{mAdc}$, $V_{CE} = -5.0 \text{Vdc}$, $f = 100 \text{MHz}$)	f_T	125	-	MHz

3. Pulse Test: Pulse Width $\leq 300 \mu\text{s}$, Duty Cycle $\leq 2.0\%$.

MMBTA63LT1G, MMBTA64LT1G, SMMBTA64LT1G

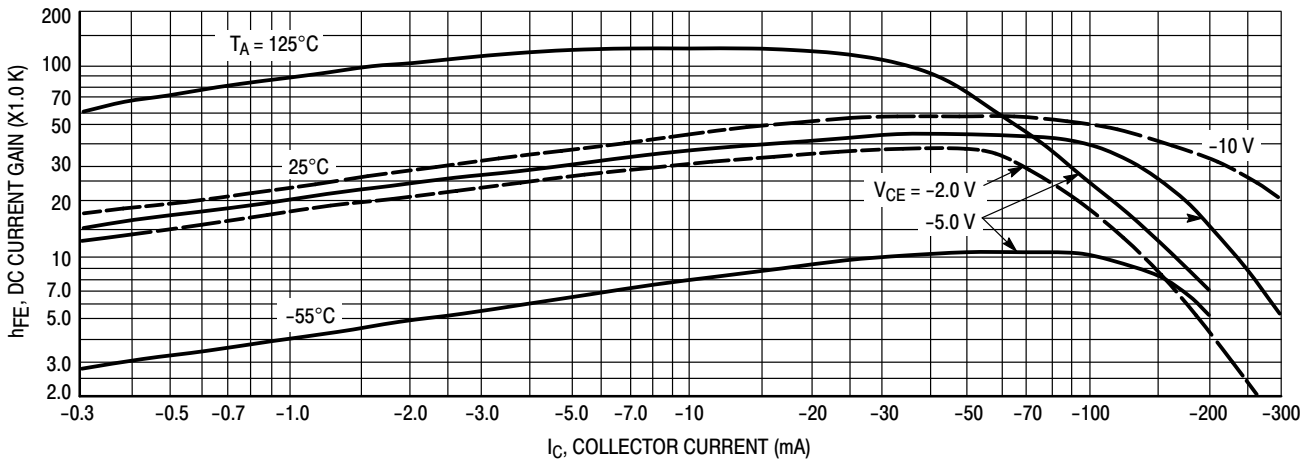


Figure 1. DC Current Gain

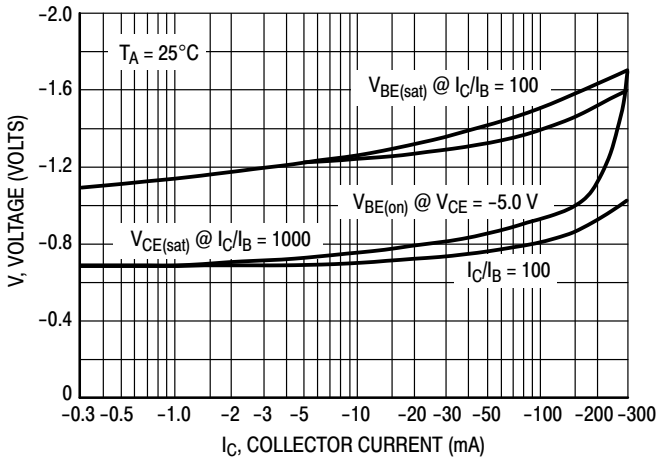


Figure 3. "On" Voltage

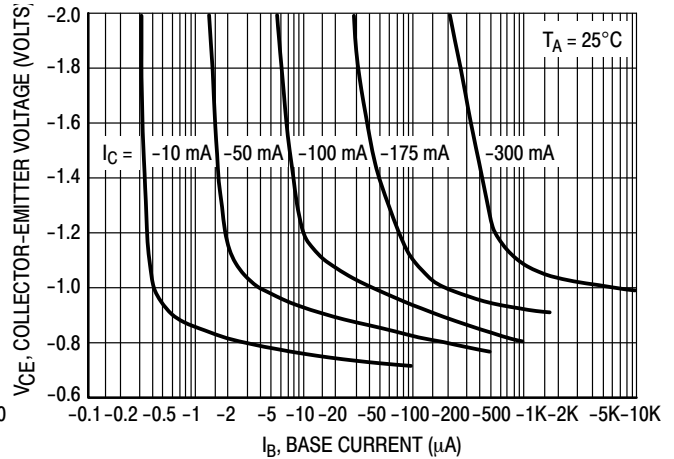


Figure 2. Collector Saturation Region

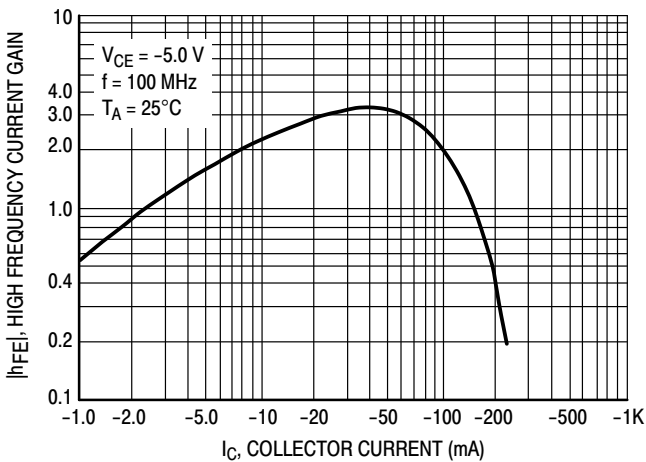


Figure 4. High Frequency Current Gain

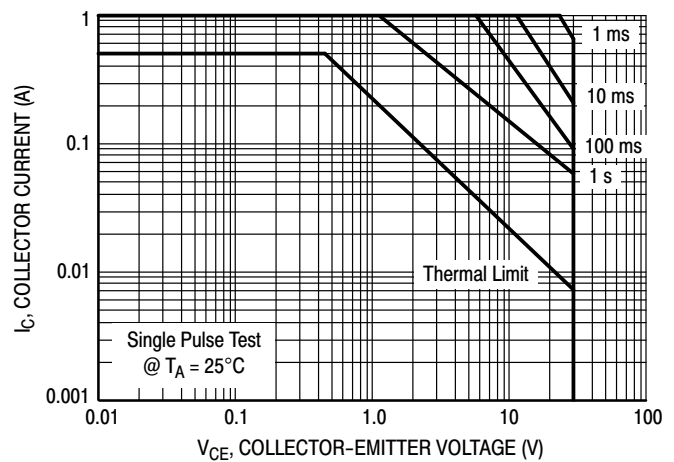
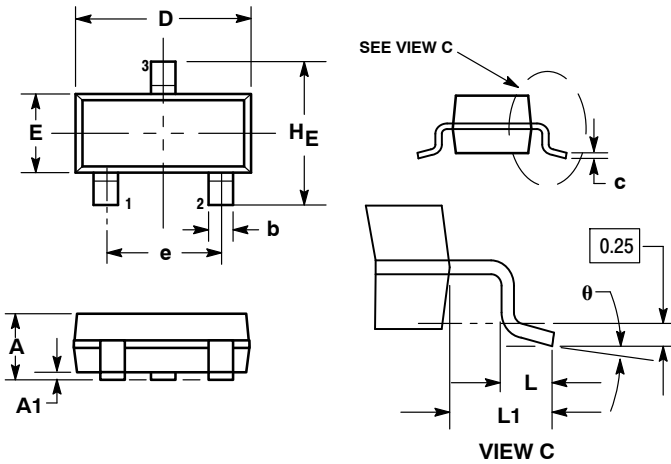


Figure 5. Safe Operating Area

MMBTA63LT1G, MMBTA64LT1G, SMMBTA64LT1G

PACKAGE DIMENSIONS

SOT-23 (TO-236)
CASE 318-08
ISSUE AP



NOTES:

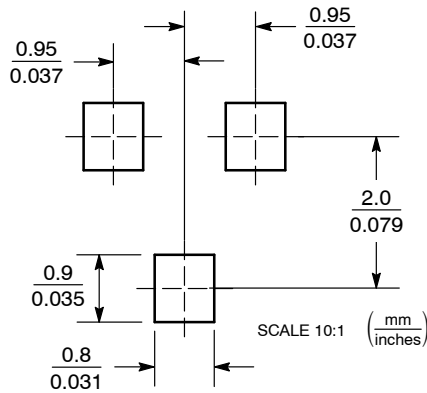
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.
4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.

DIM	MILLIMETERS			INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	0.89	1.00	1.11	0.035	0.040	0.044
A1	0.01	0.06	0.10	0.001	0.002	0.004
b	0.37	0.44	0.50	0.015	0.018	0.020
c	0.09	0.13	0.18	0.003	0.005	0.007
D	2.80	2.90	3.04	0.110	0.114	0.120
E	1.20	1.30	1.40	0.047	0.051	0.055
e	1.78	1.90	2.04	0.070	0.075	0.081
L	0.10	0.20	0.30	0.004	0.008	0.012
L1	0.35	0.54	0.69	0.014	0.021	0.029
HE	2.10	2.40	2.64	0.083	0.094	0.104
θ	0°	---	10°	0°	---	10°

STYLE 6:

1. BASE
2. EMITTER
3. COLLECTOR

SOLDERING FOOTPRINT



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